



Wen Li	Fang Yang	Jiang Yang	Fang Wang



Technical drawing of a mechanical part showing three views: front, side, and top.

Front View:

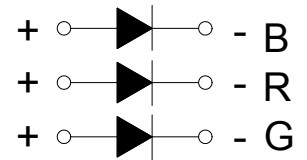
- Overall width: 5.50
- Inner width: 5.00
- Overall height: 5.00
- Central hole diameter: $\varnothing 3.74$
- Feature diameters: $\varnothing 4.40$ and $\varnothing 3.74$
- Feature thicknesses: 0.75, 1.00, and 1.50
- Feature positions: +, +, +, +

Side View:

- Overall height: 5.00
- Width: 1.50
- Feature: Polari Mark

Top View:

- Overall width: 4.40
- Slot width: 1.50
- Base width: 2.80
- Feature height: 0.80
- Feature width: 1.50



Drawing bibliography



3 Characteristic

Forward current	If	30	mA			
Reverse voltage	Vr	5	V			
Power dissipation	Pd	110	mW			
Operating temperature range	Top	-25 +80	C			
Storage temperature range	T g	-30 +80	C			
Peak pulsing current 1/8 d f=1KH	Ifp	125	mA			
Wavelength at peak emission (R)	If=20mA	peak	620	625	630	nm
Wavelength at peak emission (G)			515	520	525	
Wavelength at peak emission (B)			460	465	470	
Spectral half bandwidth	If=20mA			10		
Forward voltage (R)	If=20mA	Vf	1.8	2.0	2.4	V
Forward voltage (G)			3.0	3.3	3.6	
Forward voltage (B)			3.0	3.3	3.6	
Luminous intensity (R)	If=20mA	I	800	1000	1200	mcd
Luminous intensity (G)			3000	3500	4000	
Luminous intensity (B)			400	500	600	
Viewing angle at 50% IV	If=10mA		--	120	--	Deg
Reverse current	Vr=5V	Ir	--	--	5	A



U ef I life	-	IF=20mA	100000			H
-------------	---	---------	--------	--	--	---

Typical Electrical/Optical Characteristic Curve
(Ta=25 °C, unless otherwise noted)

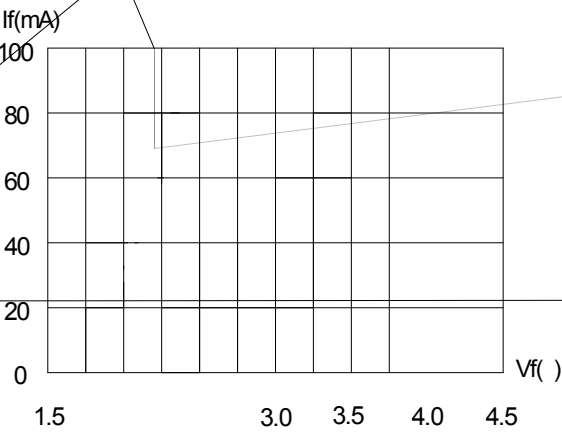


Fig.1 Forward Current vs Forward Voltage

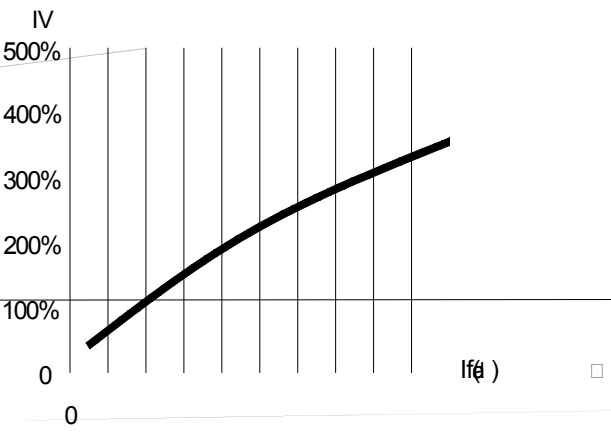


Fig.2 Relative Luminous Intensity vs Forward Current



i Iron Soldering: The Iron (max 30W) end temperature less than 300 °C, time 3 seconds, soldering position is minimum 2mm from board.

ii Dip Soldering: Max temperature 260 °C, time 5s, the position is minimum 2mm from board.

i Bracket must be soldered only if 2mm from colloid.

ii Bracket mould must be finished by fire or professional.

iii Bracket mould must be finished before soldering.

i Bracket mould should always be connected between the pin, the distance gap of lead and the circuit board.

i. I should be pay attention to the ordering of all the devices in case of wrong polarity. Devices can be too close to the heat components, working condition can replace the limit.

ii. I should not assemble LED when the leads are deformed.

iii. When decide to assemble in hole, accurately according to the size of hole and the distance of the line base.

i. Suggesting the heat positioning

i. d

